**Datacon 2200 evo hS**

**Innovative Solution for Innovative Products**

The Datacon 2200 evo hS die bonder for Multi Module Attach assembles all kinds of technologies on a tried-and-tested platform, enhanced with key features for higher bonding accuracy and lower cost of ownership.

Besides unbeaten flexibility and full customization possibilities, this evolutionary machine offers higher accuracy with long-term stability using a new camera system and thermal compensation algorithm, higher speed through a new image processing unit, and improved cleanroom capabilities.

### Datacon 2200 evo goes hS!

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**Future Proof Equipment**

- **8 WEEKS LEAD TIME**
- **HIGHEST OUTPUT** +30%
- **TOOL-TO-TOOL REPEATABILITY** T2T
- **ACCURACY** 7μ
- **MULTI-CHIP**

[www.besi.com](http://www.besi.com)
**Multi-Chip**
- Fully automatic cycle for Multi-Chip production
- Up to 7 Pick & Place tools (optionally 14), 5 eject tools
- Pressure/time (Musashi®), Auger, Jetter type dispensers available
- Epoxy stamping option
- Filled and unfilled epoxy, wide viscosity range

**Pick & Place Head**
- Die Attach, Flip Chip and Multi-Chip in one machine
- Die pick from: wafer, waffle pack, Gel-Pack®, feeder
- Die place to: substate, boat, carrier, PCB, leadframe, wafer
- Hot and cold processes supported: epoxy, soldering, thermo-compression, eutectic

**Accuracy**
- New high-speed image processing unit
- Full alignment & Bad mark search
- Pre-defined fiducial geometry & customized teaching

**Performance**
- X/Y placement accuracy: ± 7 µm @ 3s
- Theta placement accuracy: ± 0.15° @ 3s

**Bond Heads**
- Standard bond head 0° - 360° rotation
- Heated bond head (optional)

**UPH**
- up to 12000

**Footprint/ Module**
- L x D x H: 1160 mm x 1225 mm x 1800 mm
- Statistics
- Uptime > 98 %
- Yield > 99.95 %

**Wafer**
- Die size Die attach: 0.17 mm - 5 mm
- Die thickness: 0.05 mm - 2 mm
- Wafer size: 2” - 12” (50 mm - 300 mm)

**Chip Trays**
- Waffle pack / Gel-Pack® 2” x 2” and 4” x 4”
- JEDEC tray on request
- Substrates and Carriers

**Substrate working range**
- 13” x 8” (325 mm x 200 mm)